ASOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION CONNECTING	nnockburn, Illinois, A	All rights reserved un ntions.	der both leve	is docume el parts, th	nt is a declaration ne declaration end	n of the substanc compasses all lov	es within the manufactur wer level materials for wl	er listed ite hich the m	em. Note: if anufacturer l	the item is an as has engineering	sembly with lower responsibility.	
	.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distributed			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on			
Supplier Information												
mpany name* Company unique ID				Unique ID Authority			Response Date*					
onsemi	ai								2024-05-16			
Contact Name	Title - Contact			F	Phone - Contact*			Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com					
uthorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com					
Requester Item Number M	fr Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Veight*	UOM	Unit Type	
М	MMSD4148T1G SS SOD123 SWCF		H DIO 100V		2024-05-16		CN1		1.525	mg	Each	
Manufacturing Proccess Information											·	
Terminal Plating / Grid Array Material	l Terminal Base Alloy		STD-020 MSL Ra	ating	Peak Proces	A Process Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles		les		
Matte Tin (Sn) - annealed CU Alloy 1				260	С	30	second	ls 3				
Comments												
evel 1 - maximum time at peak temperature dur	ing soldering is 10-3	30 seconds										
For more information regarding material compo	sition please refer t	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.88	mg	Supplier	Silicon (Si)	7440-21-3		0.88	mg
Lead Frame	3.19	mg	В	Nickel (Ni)	7440-02-0		1.158	mg
			Supplier	Iron (Fe)	7439-89-6		1.6014	mg
			Supplier	Copper (Cu)	7440-50-8		0.4306	mg
Mold Compound-Black	6.51	mg	Supplier	Boron zinc hydroxide oxide	138265-88-0		0.1953	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.0325	mg
			Supplier	2,4,6-triamino-s-triazincompd.withs- triazine-triol	37640-57-6		0.1953	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.208	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0651	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.5208	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2929	mg
Plating	0.8	mg	Supplier	Tin (Sn)	7440-31-5		0.8	mg
Wire Bond	0.145	mg	Supplier	Palladium (Pd)	7440-05-3		0.0019	mg
			Supplier	Copper (Cu)	7440-50-8		0.1431	mg